



DPLS350E

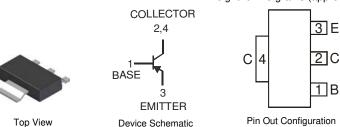
LOW V_{CE(SAT)} PNP SURFACE MOUNT TRANSISTOR

Features

- **Epitaxial Planar Die Construction**
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. • UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.115 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-60	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Emitter-Base Voltage	V _{EBO}	-6	V
Peak Pulse Current	I _{CM}	-5	A
Continuous Collector Current	Ic	-3	A
Base Current	IB	-1	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T _A = 25°C	PD	1	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ T _A = 25°C	$R_{\theta JA}$	125	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	°C

1. No purposefully added lead. Notes:

Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.



Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 4)						·
Collector-Base Cutoff Current		_	—	-100	nA	$V_{CB} = -50V, I_E = 0$
	I _{СВО}	_	_	-50	μA	$V_{CB} = -50V, I_E = 0, T_A = 150^{\circ}C$
Emitter-Base Cutoff Current	I _{EBO}	_	_	-100	nA	$V_{EB} = -5V, I_{C} = 0$
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-50	_	_	V	I _C = -100μA
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-50	_	—	V	I _C = -10mA
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5	_		V	I _E = -100μA
ON CHARACTERISTICS (Note 4)						•
DC Current Gain		200	—	—		$V_{CE} = -2V, I_{C} = -0.5A$
	h _{FE}	200	_	_		$V_{CE} = -2V, I_{C} = -1A$
		100	_	_		$V_{CE} = -2V, I_{C} = -2A$
Collector-Emitter Saturation Voltage		_	_	-100	mV	$I_{\rm C}$ = -0.5A, $I_{\rm B}$ = -50mA
	V _{CE(SAT)}	_	_	-180		$I_{C} = -1A, I_{B} = -50mA$
		_	_	-300		$I_{\rm C} = -2A, I_{\rm B} = -200 {\rm mA}$
Equivalent On-Resistance	R _{CE(SAT)}	_	67	150	mΩ	I _E = -2A, I _B = -200mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	_	_	-1.2	V	I _C = -2A, I _B = -200mA
Base-Emitter Turn-on Voltage	V _{BE(ON)}	_	_	-1.1	V	V _{CE} = -2V, I _C = -1A
SMALL SIGNAL CHARACTERISTICS						·
Transition Frequency	f _T	100	_		MHz	$V_{CE} = -5V, I_C = -100mA,$ f = 100MHz
Output Capacitance	C _{obo}	_	_	40	pF	V _{CB} = -10V, f = 1MHz

Notes: 4. Measured under pulsed conditions. Pulse width = 300μ s. Duty cycle $\leq 2\%$.

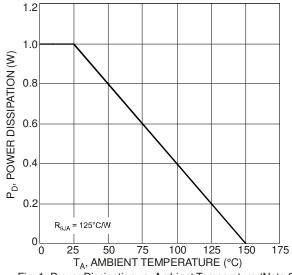
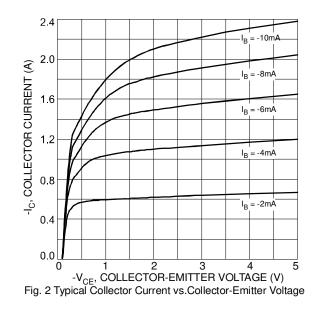
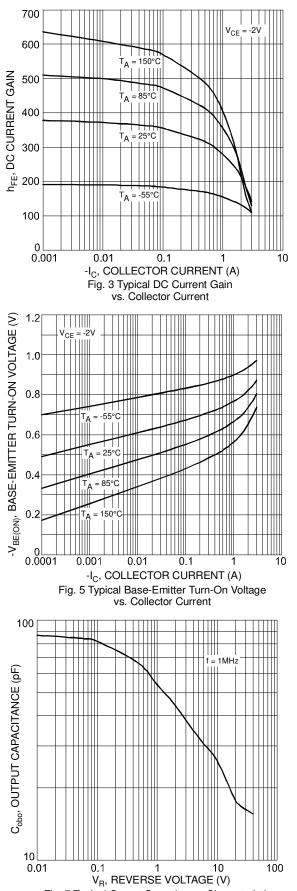


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)







-V_{CE(SAT)}, COLLECTOR-EMITTER SATURATION VOLTAGE (V) 85 √A=-= 25°C -55°C 0 0.0001 0.001 0.01 0.1 -I_C, COLLECTOR CURRENT (A) Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current - $V_{BE(SAT)}$, BASE-EMITTER SATURATION VOLTAGE (V) 1.2 $I_{\rm C}/I_{\rm B}=10$ 1.0 0.8 ΠI -55°C 0.6 111 0.4 85°C 0.2 150°0 0 0.001 0.01 0.1 1 -I_C, COLLECTOR CURRENT (A) 0.0001 0.001 Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current 240 $f_{\rm T},$ GAIN-BANDWIDTH PRODUCT (MHz) 210 180 150 120 90 60 V_{CE} = -5V f = 100MHz 30

-I_C, COLLECTOR CURRENT (mA) Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

60

80

40

0.3 10

0.2

0.1

10

10

0 0

20

100

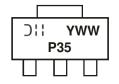


Ordering Information (Note 5)

Part Number	Case	Packaging
DPLS350E-13	SOT-223	2500/Tape & Reel

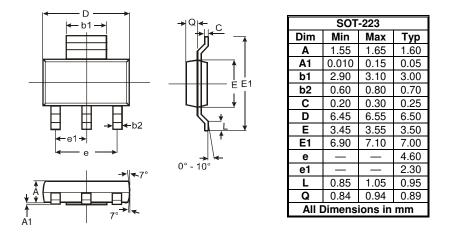
Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information

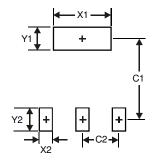


P35 = Product Type Marking Code) | = Manufacturer's Code Marking YWW = Date Code Marking Y = Last digit of year (ex: 7 = 2007) WW = Week code 01 - 52

Package Outline Dimensions



Suggested Pad Layout



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3



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